

PRODUCT DESCRIPTION

Modified Polyimide | 1 part | thermal curing | thermally conductive | electrically conductive

- Electrically conductive contacts
- Silver filled
- ► High temperature resistance
- Outstanding adhesion to gold, aluminum, tantalum, germanium and ceramics
- Low ion content (≤ 5 ppm F⁻, Cl⁻, Na⁺, K⁺)

CURING PROPERIES

This adhesive must be cured with heat. Typical curing temperatures are listed in the table below.

Temperatures	Time
120°C	4 h
150°C	1 h

After thermal curing, the product must be post-cured for 2 hours at 200 ° C. The heat cure times are only provided as a guideline. They are derived from curing a 2g adhesive sample without affixed substrates in a laboratory environment. Actual cure times can vary based on part size, configuration, adhesive volume and temperature control required for the component substrates to attain oven temperature.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.



Resin Polyimide Appearance Grey Filler Silver Filler - weight [%] 81 Uncured Material Viscosity [g/cm²] 2.7 - 2.8 Test instruction P004 2.7 - 2.8 Working life [days] 3 @ room temperature 3 Cured Material Hardness shore D Hardness shore D 50°C, 80min + 200°C, 2h 70 - 90 Test instruction P006 70 - 90 Typical operating temperature [*C] -45 - 275 Linear shrinkage [%] 50°C, 80min + 200°C, 2h 50°C, 80min + 200°C, 2h Test instruction P013 41.5 Water absorption [wt%] 50°C, 80min + 200°C, 2h 41.5 Test instruction P016 50°C, 80min + 200°C, 2h 30 - 35 Test instruction P009 20°C, 80min + 200°C, 2h 30 - 35 Test instruction P017 38 - 4.2 Test instruction P040 38 - 4.2 Test instruction P040 38 - 4.2 Test instruction P040 30 - 800	TECHNICAL DATA	
Appearance Grey Filler Filler - weight [%] 81 Uncured Material Viscosity [mPas] Paste-like Density [g/cm³] 2.7 - 2.8 Working life [days] 3 @ room temperature 3 Cured Material Hardness shore D 150°C, 60min + 200°C, 2h 70 - 90 Test instruction PO06 70 Typical operating temperature [°C] -45 - 275 Linear shrinkage [%] 5 150°C, 60min + 200°C, 2h <5		
Filler - weight [%] Silver Filler - weight [%] 81 Uncured Material Viscosity [mPas] Paste-like Density [g/cm²] 2.7 - 2.8 Working life [days] 3 2 @ room temperature 3 4 Cured Material 4 70 - 90 Hardness shore D 150°C, 60min + 200°C, 2h 70 - 90 Test instruction PO06 70 - 90 70 - 90 Typical operating temperature [°C] -45 - 275 Linear shrinkage [%] 4 5 150°C, 60min + 200°C, 2h 4 5 test instruction PO15 4 5 Water absorption [wt%] 15 15 150°C, 60min + 200°C, 2h 4 15 Test instruction PO16 3 180 Glass transition temperature - DSC [°C] 180 Est instruction PO17 30 - 35 Test instruction PO17 30 - 35 Test instruction PO29 30 - 35 Volume resistivity [Ohm*cm] 150°C, 60min + 200°C, 2h 3.8 - 4.2 Test instruction PO40 <	Resin	Polyimide
Filler - weight [%] S1 Uncured Material Viscosity [mPas] Paste-like Density [g/cm²] 2.7 - 2.8 Test instruction P004 3.7 - 2.8 Working life [days] 3 Ø room temperature Cured Material Hardness shore D 150°C, 60min + 200°C, 2h 70 - 90 Typical operating temperature [°C] -45 - 275 Linear shrinkage [%] 55°C, 60min + 200°C, 2h 55°C, 60min + 200°C, 2h 515°C, 60min	Appearance	Grey
Uncured Material	Filler	Silver
Paste-like	Filler - weight [%]	81
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Test instruction P004 Working life [days]	Density [g/cm³]	27 20
© room temperature 3 Cured Material 70 - 90 Hardness shore D 70 - 90 150°C, 60min + 200°C, 2h 70 - 90 Typical operating temperature [°C] -45 - 275 Linear shrinkage [%] (5 150°C, 60min + 200°C, 2h (5 Test instruction P031 (15 Water absorption [wt%] (15 150°C, 60min + 200°C, 2h (15 Test instruction P016 ×180 Glass transition temperature - DSC [°C] ×180 Test instruction P009 ×180 Coefficient of thermal expansion [ppm/K] below Tg 30 - 35 Test instruction P007 30 - 35 Test instruction P017 3.8 - 4.2 Test instruction P062 Volume resistivity [Ohm*cm] 150°C, 60min + 200°C, 2h 1 x 10-4 - 3 x 10-4 Test instruction P040 1x 10-4 - 3 x 10-4 Storage modulus - DMA [MPa] 150°C, 60min + 200°C, 2h 600 - 800 600 - 800		2.7 – 2.8
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150°C, 60min + 200°C, 2h >180	Test instruction P016	
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Test instruction P040 Storage modulus – DMA [MPa] 150°C, 60min + 200°C, 2h 600 – 800	•	
Storage modulus – DMA [MPa] 150°C, 60min + 200°C, 2h 600 – 800		$1 \times 10^{-4} - 3 \times 10^{-4}$
150°C, 60min + 200°C, 2h 600 – 800	Test instruction P040	
150°C, 60min + 200°C, 2h 600 – 800	Storage modulus – DMA [MPa]	
Test instruction PO22		600 – 800
	Test instruction PO22	



TRANSPORT/STORAGE/SHELF LIFE

Package type	Transport	Storage	Shelf life*
Syringe/Cartridge	-20°C	≤ -20°C	At delivery min. 6 months max. 12 months
Other packages	At room temperature max. 25°C	0°C – 10°C	

^{*}Store in original, unopened containers!

INSTRUCTIONS FOR USE

Elecolit® 327 must be homogenized after transport at room temperature or storage at 0°C – 10°C, because the filler can sediment. In case of crystallization, it can be reversed by heating to 60°C.

N-methylpyrrolidone dissolves most plastics, so the processing equipment should be made of glass, stainless steel, polyethylene or polypropylene.

Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP® from Hoenle, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

Application

Our products are supplied ready to use. Depending on the packaging, our adhesives may be dispensed by hand directly from the package, or they can be applied using dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. Adhesive and substrate should not be cold for proper bonding. They must be allowed to warm to room temperature prior to processing. After curing, the adhesive must be allowed to cool to ambient temperature before testing the product's performance. For safety information refer to our Material Safety Data Sheet (MSDS).

Storage

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Hoenle cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!



DISCLAIMER

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

THE VALUES NOTED IN THIS TECHNICAL DATA SHEET ARE TYPICAL PROPERTIES AND ARE NOT MEANT TO BE USED AS PRODUCT SPECIFICATIONS.

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